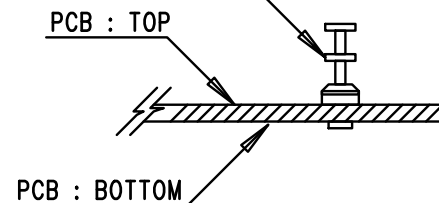


NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
MAXIMUM SOLDER TEMPERATURE IS 240 DEG C.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS.
LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER.
MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE
BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP
TO ANY BOARD.

TURRETS : MILL-MAX 2501-2



TITLE: TOP ASSEMBLY DRAWING
LOW-IQ NO-OPTO ISOLATED
FLYBACK CONTROLLER

SIZE	IC NO.	REV.
N/A	LT8306 EVAL-LT8306-AZ	4

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